2016 IEEE Workshop on Microelectronics & Electron Devices   April 15, 2016

Boise State University, Jordan and Simplot Ballrooms, Boise, Idaho, USA

WMED Highlights:
- Two parallel tutorials: Process & Circuit
- Best paper and poster awards
- 400+ Attendees
- Parallel High School Engineering Program
- Past Invited Speakers:
    - Chenming Hu, UC Berkeley
    - Chris Mack, The Litho Guru
    - Rahul Sarpeshkar, MIT
    - Lakshman Krishnamurthy, Intel
    - Bradley Howard, Applied Materials

Important Dates:
- Manuscript submission: 1/25/2016
- Advance registration: 4/1/2016
- Conference date: 4/15/2016

UNIVERSITY TRAVEL AWARD
Attendees and Participants are eligible for a Travel Subsidy (up to $500).

Contact WMED Publications Chair, Shu Qin (sqin@micron.com , +1 208-368-2144) for details.

International Authors: If you require a US VISA and letter of acknowledgment from WMED in order to attend the workshop and present your paper, we strongly urge that you submit your manuscript early (Recommended manuscript submission by 12/30/2015) and request "expedited review".

WMED 2016 - Call For Papers

The **Fourteenth** Annual IEEE Workshop on Microelectronics and Electron Devices (WMED) will provide a forum for reviewing and discussing all aspects of micro- and nano-electronics including processing, electrical characterization, design and new device technologies. This workshop will consist of invited and contributed talks, papers and a poster session throughout the day. Faculty, students and researchers in industry are encouraged to contribute papers on either completed research or work in progress. Topics in the following areas will form the contributing sessions and poster session in the workshop:

Microelectronic Device Processing and Process Integration
Trends in submicron CMOS technology, product development (DRAM, SRAM, Flash, CMOS Imagers), new device technologies (phase change memory, resistive memory, ferroelectric memory), novel transistors

Nanoelectronic Devices and MEMS
Novel processes, materials and device characterization on nanotubes, nanowires, quantum dots, molecular devices, MEMS research

Microelectronic Device Electrical and Reliability Testing
Dielectric reliability, device reliability, novel memory technology testing schemes

Semiconductor Packaging and Reliability
Semiconductor package reliability, design for manufacturability, stacked die packaging and novel assembly processes

Microelectronic Circuit and System Design
New product design, high-speed and low-power design techniques and system architectures and memory sensing schemes

An IEEE Publication of the accepted papers and a USB Flash Drive including the papers and presentations are planned and will be available at the start of the workshop. Submitted manuscripts must follow the IEEE publication format guidelines. A template containing manuscript preparation instructions can be downloaded here:

Download Manuscript Template

Please submit your IEEE-formatted manuscript (up to 4 pages) by **January 25th, 2016** to the WMED Publications Chair, Shu Qin (sqin@micron.com, +1 208-368-2144). The Technical Program Committee will have a peer-review process to meet the IEEE criterion for minimum standards of publication quality. Conference details are online at website: http://www.ewh.ieee.org/r6/boise/wmed2016/WMED2016.html. Inquiries can be directed to: Yantao Ma (IEEE WMED 2016 General Chair, yantaoma@micron.com, +1 208-363-3222).

This workshop is receiving technical co-sponsorship support from the IEEE Electron Devices Society.